

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1-8. (canceled).

9. (currently amended): ~~The A-multilayer printed circuit board according to claim 7 or claim 8, comprising:~~

a conductor circuit and resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and a solder resist layer formed as an outermost layer,

wherein, said solder resist layer contains an elastomer component in a composition comprising a resin for said solder resist layer, and

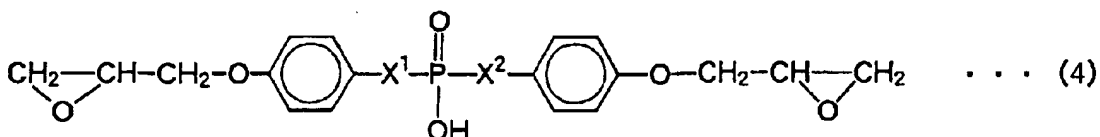
said elastomer component is separated in micro-phase as to form an island-in-sea structure after curing in said solder resist layer.

10-30. (canceled).

31. (currently amended): ~~The multilayer printed circuit board according to claim 30~~
A multilayer printed circuit board comprising: a conductor circuit and resin insulation layer serially formed on a substrate in an alternate fashion and in repetition; and a solder resist layer formed as an outermost layer,

wherein said solder resist layer contains a P atom-containing epoxy resin, and
said P atom-containing epoxy resins has bivalent phosphoric acid residue, and has epoxy
groups in both terminals.

32. (original): The multilayered printed circuit board according to claim 31,
wherein said epoxy resin having bivalent phosphoric acid residue and having epoxy
groups in both terminals is an epoxy resin having the following general formula [4]



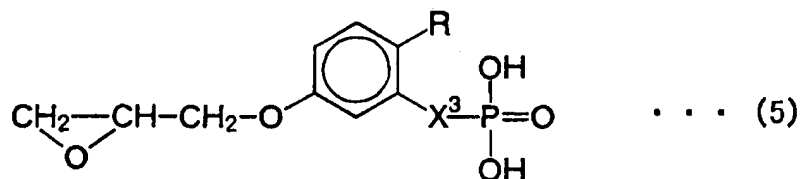
(wherein X¹, X² respectively represent O or a single bond).

33. (currently amended): ~~The~~ A multilayered printed circuit board comprising:
~~according to claim 30,~~ a conductor circuit and a resin insulating layer serially formed on a
substrate in an alternate fashion and in repetition; and solder resist layer formed as an outermost
layer,

wherein said solder resist layer contains a P atom-containing epoxy resin, and
said P atom-containing epoxy resin is an epoxy resin having a monovalent phosphoric
acid residue in one terminal and an epoxy group in the other terminal.

34. (currently amended): The multilayered printed circuit board according to claim 33,

wherein said epoxy resin having a monovalent phosphoric acid residue in one terminal and an epoxy group in the other terminal is an epoxy resin having the following general formula [5]:



[[:]](wherein X³ represents O or a single bond; and R represents an alkyl of 2 to 8 carbons).

35. (currently amended): The multilayered printed circuit board ~~according to any of~~
claims 30 to 34, comprising: a conductor circuit and a resin insulating layer serially formed on a
substrate n an alternate fashion and in repetition; and solder resist layer formed as an ortermost
layer.

wherein said solder resist layer contains a P atom-containing epoxy resin, and at least one member selected from the group consisting of a silicon compound, an aluminum compound and a magnesium compound.

36. (new): A multilayer printed circuit board comprising:
a conductor circuit and a resin insulating layer serially formed on a substrate in an
alternate fashion and in repetition; and a solder resist layer formed as an outermost layer,
wherein said solder resist layer contains an elastomer component in a composition
comprising a resin for said solder resist layer,
said elastomer component is at least one member selected from the group consisting of
natural rubber, synthetic rubber, a thermoplastic resin and a thermosetting resin, and
said elastomer component is separated in micro-phase as to form an island-in-sea
structure after curing in said solder resist layer.